

SMD ■ Mini Top View LEDs 65-11-GBC-Y0V1AAN0E-2T8-AM



Features

- P-LCC-2 package.
- Colorless clear resin.
- Wide viewing angle 120°.
- Inner reflector and white package.
- Brightness: 710 to 1400mcd at 20mA
- Precondition: Bases on JEDEC J-STD 020D Level 2
- Qualification according to AEC-Q101 rev C.
- Automotive reflow profile (IR reflow or wave soldering)

Applications

- Automotive backlighting or indicator: Dashboard, switch, audio and video equipments...etc.
- Backlight: LCD, switches, symbol, mobile phone and illuminated advertising.
- Display for indoor and outdoor application.
- Ideal for coupling into light guides.
- Substitution of traditional light.
- Optical indicator.

Device Selection Guide

Chip Materials	Emitted Color	Resin Color
InGaN	Brilliant Green	Water Clear

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	30	mA
Peak Forward Current (Duty 1/10 @1KHz)	I_{FP}	100	mA
Power Dissipation	P_d	120	mW
Junction Temperature	T_j	125	°C
Operating Temperature	T_{opr}	-40 ~ +100	°C
Storage Temperature	T_{stg}	-40 ~ +110	°C
Thermal Resistance	$R_{th\ J-A}$	600	K/W
	$R_{th\ J-S}$	400	K/W
ESD (Classification acc. AEC Q101)	ESD_{HBM}	2000	V
	ESD_{MM}	200	V
Soldering Temperature	T_{sol}	Reflow Soldering : 260 °C for 30 sec. Hand Soldering : 350 °C for 3 sec.	

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	Iv	710	-----	1400	mcd	I _F =20mA
Viewing Angle	2θ _{1/2}	-----	120	-----	deg	I _F =20mA
Peak Wavelength	λp	-----	536	-----	nm	I _F =20mA
Dominant Wavelength	λd	520	-----	535	nm	I _F =20mA
Spectrum Radiation Bandwidth	Δλ	-----	35	-----	nm	I _F =20mA
Forward Voltage	V _F	2.7	-----	3.7	V	I _F =20mA

Note:

1. Tolerance of Luminous Intensity: ±11%
2. Tolerance of Dominant Wavelength: ±1nm
3. Tolerance of Forward Voltage: ±0.1V

Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
V1	710	900	mcd	I _F =20mA
V2	900	1120		
AA	1120	1400		

Note:

Tolerance of Luminous Intensity: ±11%

Bin Range of Dominant Wavelength

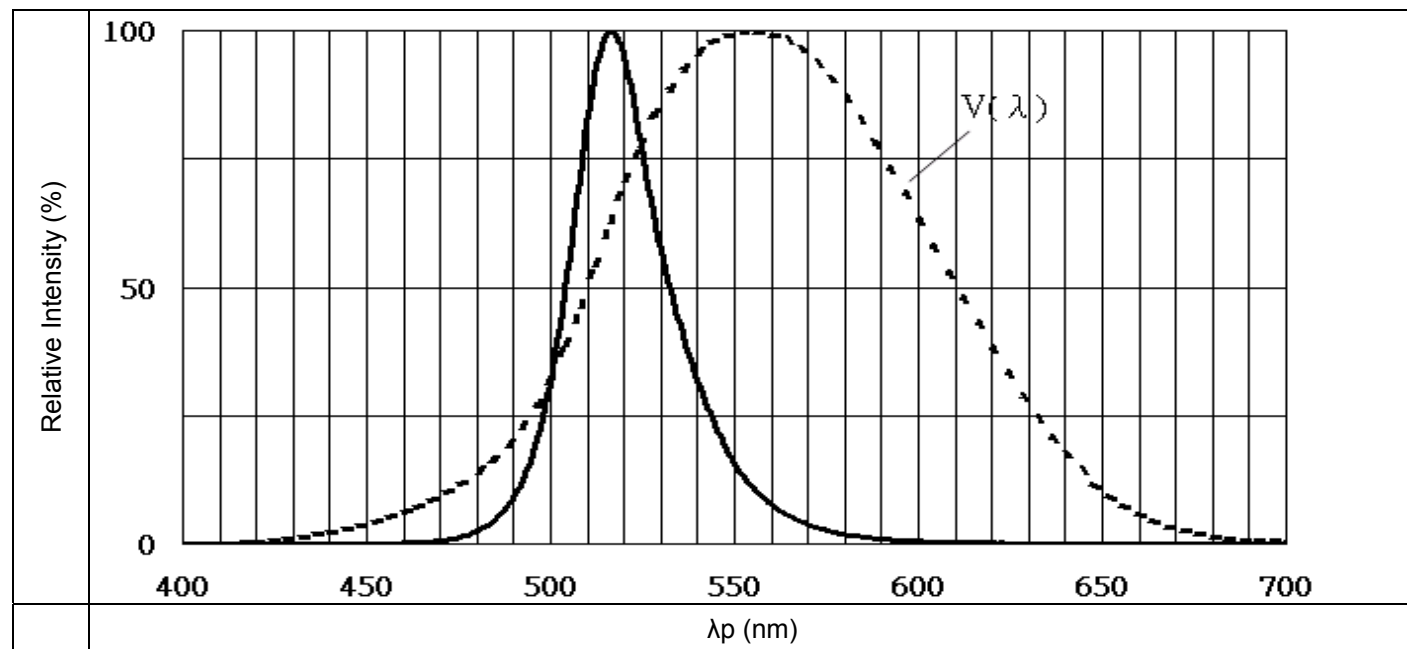
Bin Code	Min.	Max.	Unit	Condition
X	520	525	nm	I _F =20mA
Y	525	530		
Z	530	535		

Note:

Tolerance of Dominant Wavelength: ±1nm

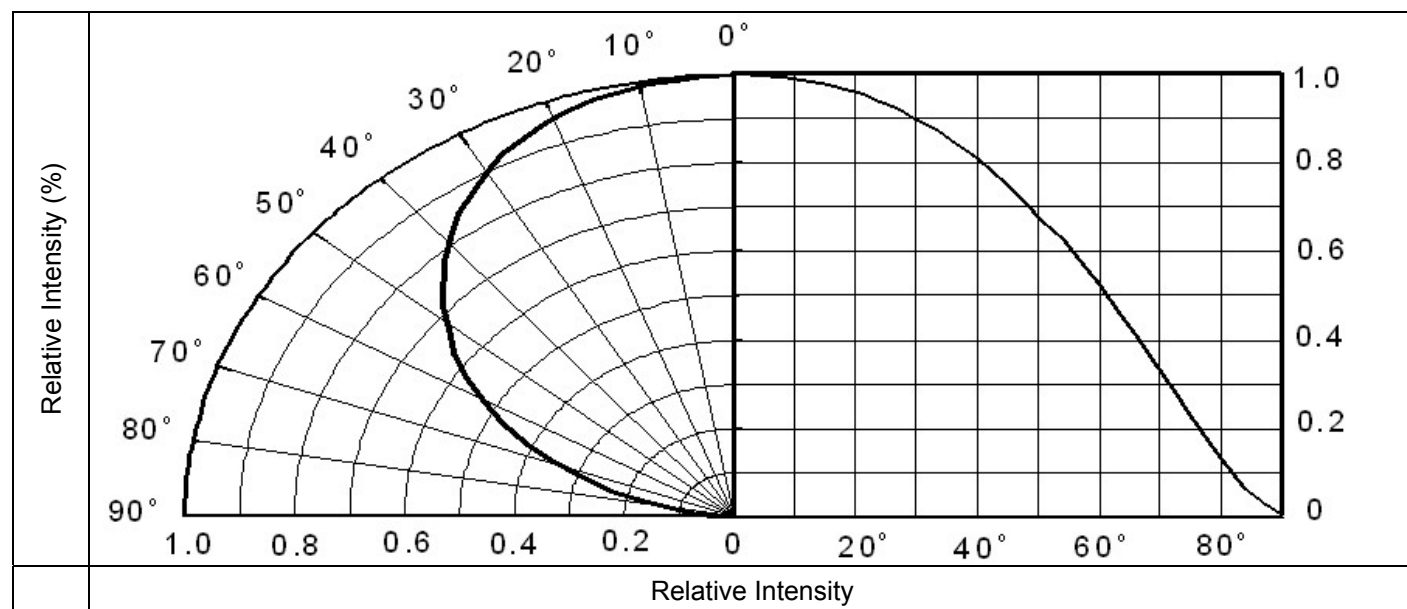
Typical Electro-Optical Characteristics Curves

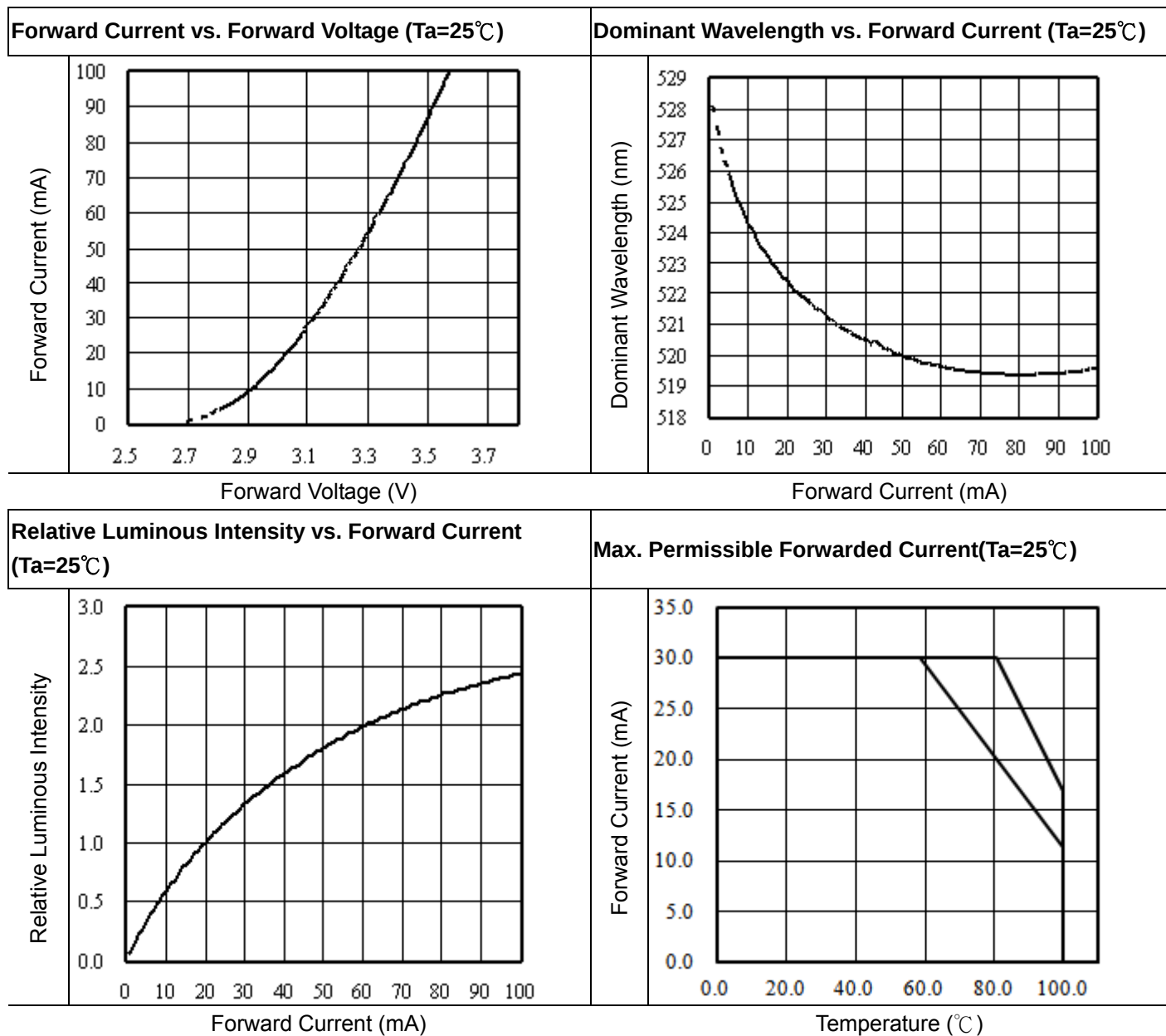
Typical Curve of Spectral Distribution



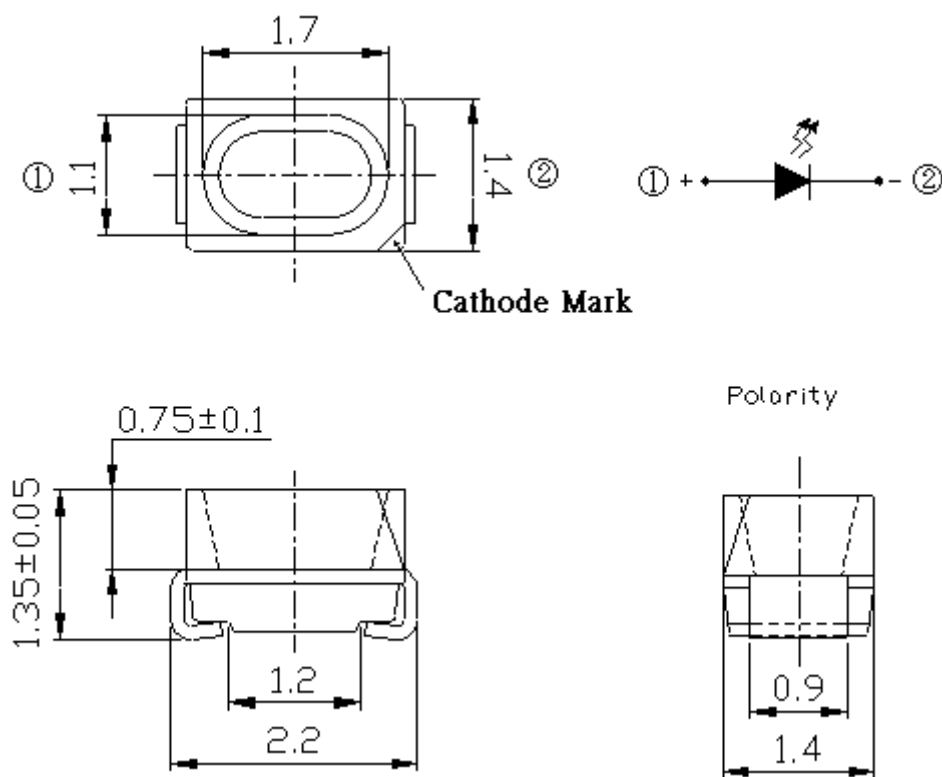
Note: $V(\lambda)$ =Standard eye response curve; $I_F = 20\text{mA}$

Diagram Characteristics of Radiation



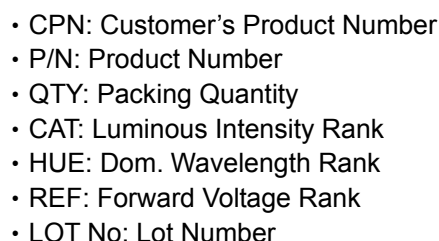


Package Dimension



Note: Tolerances unless mentioned ± 0.1 mm. Unit = mm

Label Explanation



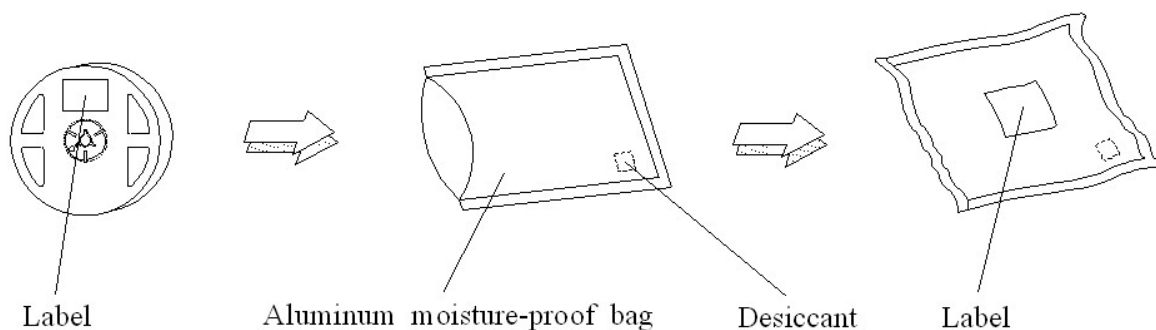
Technical drawing of a circular component. The drawing includes the following dimensions and features:

- Top horizontal dimension: 2.2 ± 0.5
- Bottom horizontal dimension: 13.0 ± 0.5
- Right vertical dimension (total): $\varnothing 78.0 \pm 1.0$
- Right vertical dimension (inner section): 9.0 ± 1.0
- Right vertical dimension (bottom section): 12.0 ± 1.0
- Inner circular feature dimension: $\varnothing 60.0 \pm 1.0$
- Central feature: A label box containing the word "Label" is positioned over a central assembly.

Technical drawing of a 5-pin connector. The drawing shows a top view and a side view. The top view includes dimensions: 1.75±0.1 (height), 2.0±0.05 (pitch), 4.0±0.1 (pitch), 4.0±0.1 (pitch), 1.52±0.1 (pitch), 1.5±0.1 (hole diameter), 3.5±0.05 (height), 8.0+0.3/-0.1 (total height), and 2.31±0.1 (height). The side view shows a 1.57±0.1 (height). The drawing also includes a polarity symbol and a progressive direction arrow.

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Moisture Resistant Packing Process

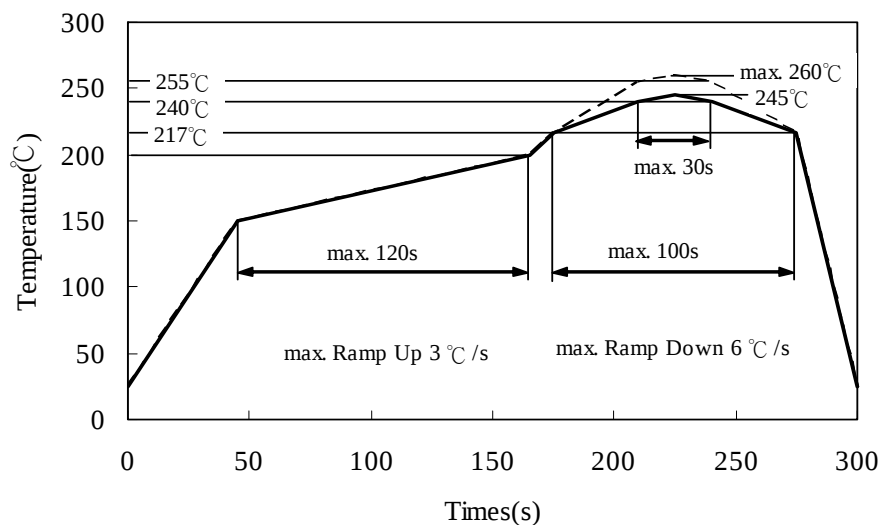


Note: Tolerances unless mentioned $\pm 0.1\text{mm}$. Unit = mm

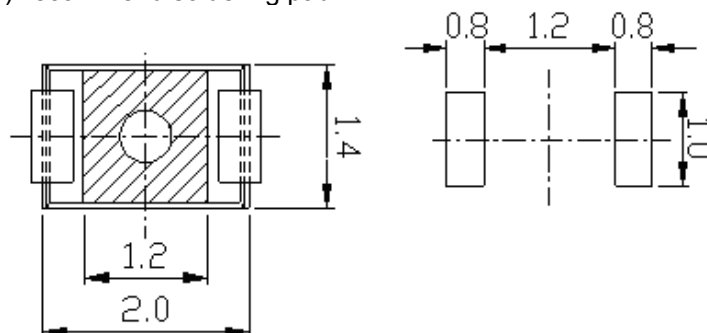
Precautions for Use

1. Soldering Condition (Reference: IPC/JEDEC J-STD-020D)

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



(B) Recommend soldering pad



Note: Tolerances unless mentioned $\pm 0.1\text{mm}$. Unit = mm

2. Current limiting

A resistor should be used to limit current spikes that can be caused by voltage fluctuations. Otherwise damage could occur.

3. Storage

3.1 Moisture proof bag should only be opened immediately prior to usage.

3.2 Environment should be less than 30°C and 60% RH when moisture proof bag is opened.

3.3 After opening the package MSL Conditions stated on page 1 of this spec should not be exceeded.

3.4 If the moisture sensitivity card indicates higher than acceptable moisture, the component should be baked at min. 60deg +/-5deg for 24 hours.

4. Iron Soldering

Hand soldering is not recommended for regular production. These guidelines are for rework only. Soldering iron tip should contact each terminal no more than 3 sec at 350°C, using soldering iron with nominal power less than 25W. Allow min. 2 sec. between soldering intervals.

5. Usage

Do not exceed the values given in this specification.

Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.

Revision History

Rev.	Modified date	File modified contents
1	2012/04/23	New Spec
2	2013/06/05	Change the new template